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Attorney Docket No. 102416-108
U.S. Serial No. 10/536,859
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This listing of claims will replace all prior versions, and listings, of claims in the application:

Complete Listing of Claims:

1. (Currently amended) An integrated circuit device package (10), comprising:
 - an integrated circuit device (12) having an electrically active surface (16) and an opposing backside surface (14) and sides (17) extending therebetween, said electrically active surface (16) having a plurality of electrically active circuit traces formed thereon and metallized bumps (18) extending from selected sites on said circuit traces, and said sides including at least one feature that is effective to limit the ingress of moisture along an interface between said integrated circuit device and a dielectric molding resin, mechanically lock said integrated circuit device to said dielectric molding resin and cause said backside surface area to be less than said electrically active surface area;
 - a plurality of electrically conductive leads (20) each having respective first surfaces and opposing second surfaces;
 - a plurality of electrical contacts (24) extending outward from said respective first surfaces;
 - a solder (22) electrically and mechanically bonding said metallized bumps (18) to said second surfaces; and
 - [a] said dielectric molding resin (26) formed into a package at least partially encapsulating said integrated circuit device (12) and said plurality of electrically conductive leads (20), said backside surface (14) and said plurality of electrical contacts (24) are exposed on opposing sides of said package.
2. (Canceled)
3. (Currently amended) The package (10) of claim [2] 1 wherein said at least one feature includes two elements (58, 60) that intersect at an angle of approximately 90°.

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4. (Currently amended) The package (10) of claim [2] 1 wherein a thickness of said package (10) is less than three times a thickness of said integrated circuit device (12).
5. (Currently amended) The package (10) of claim 4 wherein said thickness of said package (10) is approximately 0.01 inch.
6. (Currently amended) The package (10) of claim [2] 1 wherein said integrated circuit device (12) is a sensor responsive to external stimulus.
7. (Currently amended) The package (10) of claim 6 wherein said external stimulus is a touch.
8. - 18. (canceled)